TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSII)

TPC8303

Lithium-Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Low drain-source ON resistance : RDS (ON) = 27 m Ω (typ.)

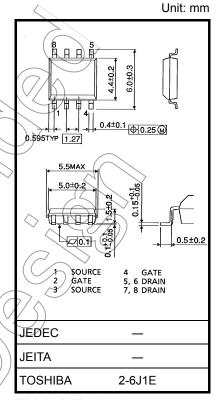
• High forward transfer admittance : $|Y_{fs}| = 7 S \text{ (typ.)}$

• Low leakage current $:I_{DSS} = -10 \mu A \text{ (max.)} \text{ (V}_{DS} = -30 \text{ V)}$

• Enhancement mode : $V_{th} = -0.8 \sim -2.0 \text{ V}$ ($V_{DS} = -10 \text{ V}$, $I_{D} = -1 \text{ mA}$)

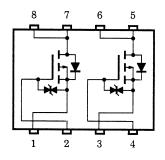
Absolute Maximum Ratings (Ta = 25°C)

				I(I/I)
Char	acteristics	Symbol	Rating	Unit
Drain-source volt	tage	V_{DSS}	-30	V
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V_{DGR}	₹30	> v
Gate-source volt	age	V _{GSS}	±20	V
	DC (Note 1)	I _D	-4.5	
Drain current	Pulse (Note 1)	I _{DP}	-18	A
Drain power dissipation	Single-device operation (Note 3a)	P _D (1)	1.5	W
(t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D(2)}	1.0	
Drain power dissipation (t = 10s) (Note 2b)	Single-device operation (Note 3a)	PD (1)	0.75	W
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45	VV
Single-pulse ava	lanche energy (Note 4)	E _{AS}	26	mJ
Avalanche curre	nt	IAR	-4.5	Α
Repetitive avalar Single-device va (Note		EAR	0.10	mJ
Channel tempera	ature	Toh	150	°C
Storage tempera	ture range	T _{stg}	-55~150	°C



Weight: 0.08 g (typ.)

Circuit Configuration



Note: For Notes 1 to 5, see the next page.

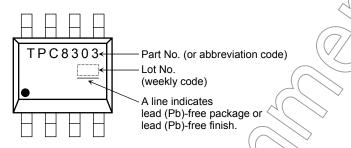
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

Thermal Characteristics

Characteristics	Symbol	Max	Unit	
The sweet resistance about all the ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3	°C/W
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	125	
Thermal registance, showned to ambigue	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	
Thermal resistance, channel to ambient (t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	278	

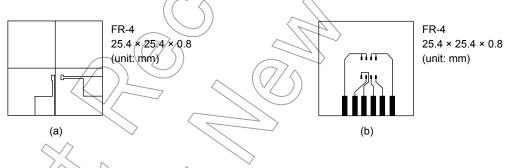
Marking (Note 6)



Note 1: Ensure that the channel temperature does not exceed 150°C

Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values shown are for a single device. (During single-device operation, power is applied to one device only.)
- b) The power dissipation and thermal resistance values shown are for a single device.

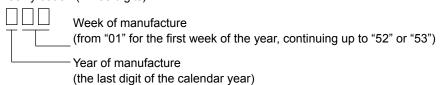
 (During dual operation, power is applied to both devices evenly.)

Note 4:
$$V_{DD} = -24 \text{ V}$$
, $T_{ch} = 25^{\circ}\text{C}$ (initial), $L = 1.0 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = -4.5 \text{ A}$

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6: ● on lower left of the marking indicates Pin 1.

* Weekly code: (Three digits)



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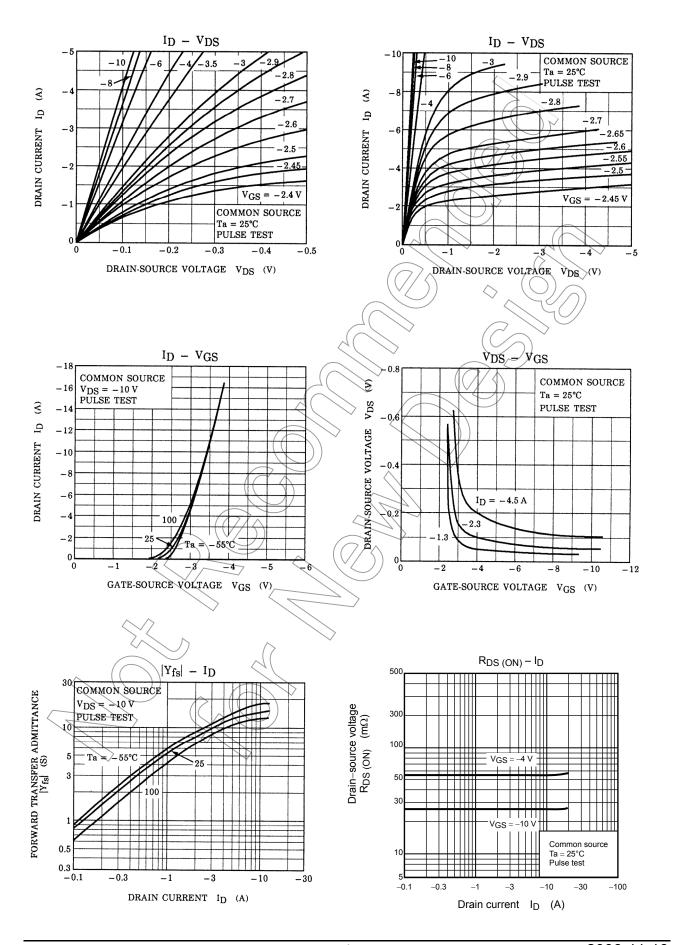
Electrical Characteristics (Ta = 25°C)

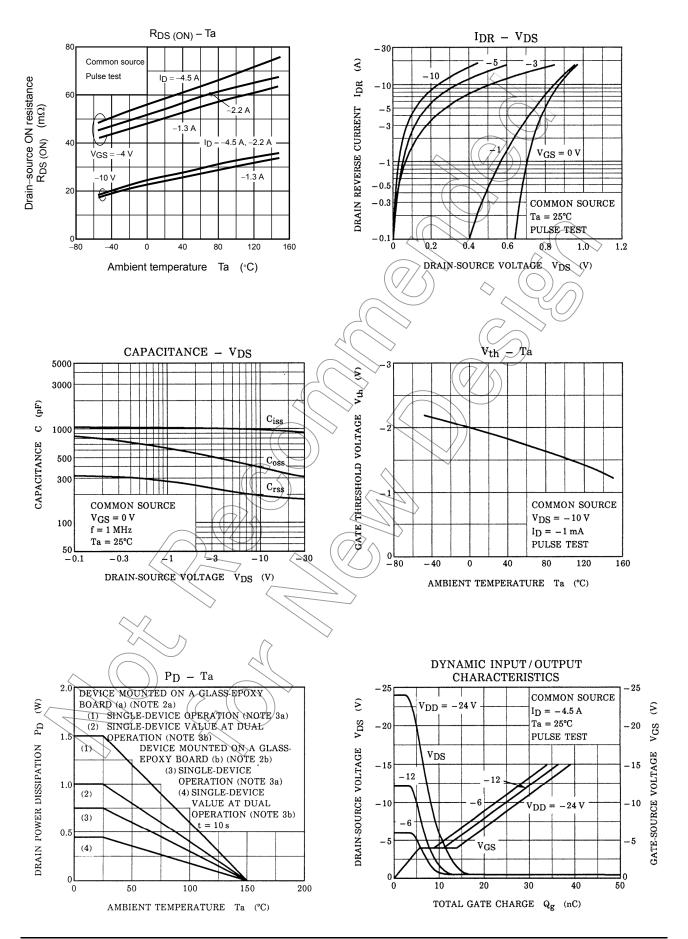
Charac	cteristics	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μA
Drain-source br	eakdown voltage	V _{(BR) DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-30	_	_	V
Diani Source bi	eardown voltage	V _{(BR) DSX}	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-15			V
Gate threshold v	/oltage	V_{th}	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	20.8) >_	-2.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = -4 V, I _D = -2.2 A	<u> </u>	55	65	mΩ
Dialii-source Of	iv resistance	R _{DS} (ON)	V _{GS} = -10 V, I _D = -2.2 A	$\bigcirc)$	27	35	11122
Forward transfer	r admittance	Y _{fs}	V _{DS} = -10 V, I _D = -2.2 A	3.5	7		S
Input capacitano	e	C _{iss}		^ —	970	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = −10 V, V _{GS} = 0 V, f = 1 MHz	_	180	_	pF
Output capacitance		Coss			370	\nearrow	
Switching time	Rise time	t _r	V _{GS} 0 V 1D=-2.2 A V _{OUT}		17	_ <	
	Turn-on time	t _{on}	VOUT R _L = 6.8 Ω		20	_	ns
	Fall time	t _f	4, , , ,		75		115
	Turn-off time	t _{off}	$V_{DD} = -15V$ $\text{Duty} \leq 1\%, \ t_{W} = 10 \mu\text{s}$) _	160	_	
Total gate charg plus gate-drain)		Q _g		_	28	_	
Gate-source charge		Qgs	$V_{DD} \approx -24 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -4.5 \text{ A}$		16	_	nC
Gate-drain ("miller") charge		Qgd		_	12	_	

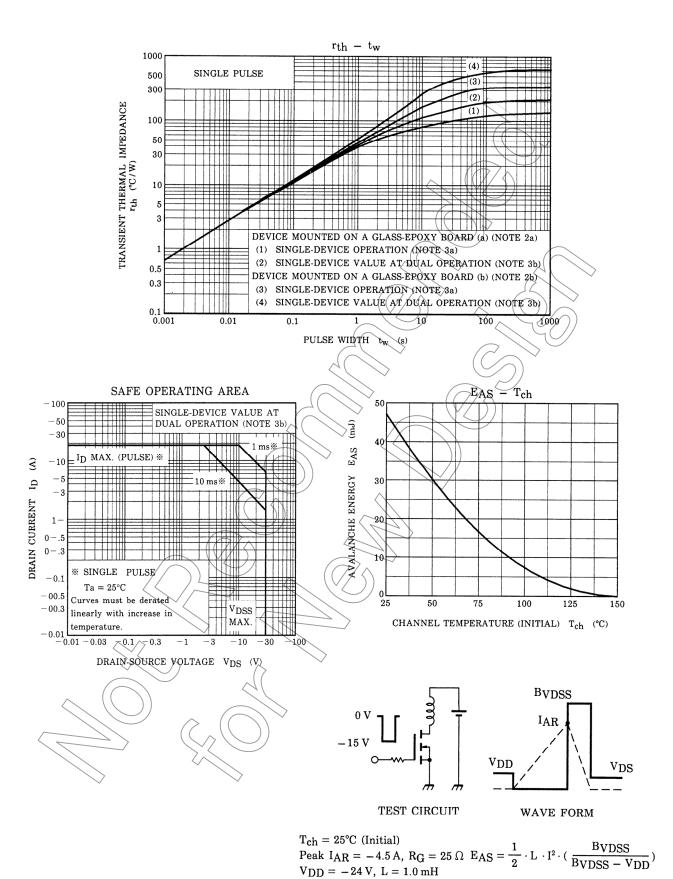
Source-Drain Ratings and Characteristics (Ta = 25°C)

Charact	teristics	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	-	_	-18	Α
Forward voltage	(diode)	V _{DSF}	$I_{DR} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.2	V











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